

15. (NEW) A method of fabricating a piezoelectric/electrostrictive device according to claim 6, wherein said method includes a step of laminating on a surface constituting the outermost layer of said ceramic green laminate having at least one hole, when laminating at least a plurality of ceramic green sheets having at least a hole formed thereon, a ceramic green sheet having at least one hole formed thereon which is mounted on a plastic film in such a manner that said plastic film is placed as a new outermost layer, and removing said plastic film after the holes are accurately aligned.

16. (NEW) A method of fabricating a piezoelectric/electrostrictive device according to claim 10, wherein said plastic film is a poly(ethyleneterephthalate) film.

17. (NEW) A method of fabricating a piezoelectric/electrostrictive device according to claim 6, wherein a ceramic laminate with a piezoelectric/electrostrictive element formed on the outer surface of said thin plate portion thereof is further cut into a desired unit individually, then thus cut units are heat treated at 300°C to 800°C.

18. (NEW) A method of fabricating a piezoelectric/electrostrictive device according to claim 6, wherein, when cutting a ceramic laminate with said piezoelectric/electrostrictive element formed thereon, said piezoelectric/electrostrictive element and said laminate are simultaneously cut, and the widths of said piezoelectric/electrostrictive element and a thin plate portion of said laminate are made the same.